



- △.000050 MIN THK NICKEL UNDERPLATE OVER ENTIRE CONTACT.
- △.000150 MIN BRIGHT TIN/LEAD OVER ENTIRE CONTACT.
- △.000100 MIN THK BRIGHT TIN/LEAD IN ZONE 1.
- △GOLD FLASH IN LOCALIZED GOLD PLATE AREA.
- △.000015 MIN GOLD IN LOCALIZED GOLD PLATE AREA
- △.000030 MIN GOLD IN LOCALIZED GOLD PLATE AREA
- 7. TO BE APPLIED PER AMP APPLICATION SPEC 114-16015.
- 8. RECOMMENDED HOLE SIZE IS .031-.035 DIA. FOR SOLDERABILITY SEE AMP PRODUCT SPEC 108-9024.
- △.000150 MIN TIN-LEAD IN ZONE 2.
- △.000150 MIN TIN-LEAD IN ZONE 1.
- △.000150 MIN TIN IN ZONE 3.
- △GOLD FLASH IN ZONE 1.
- △GOLD FLASH IN ZONE 2.
- △GOLD FLASH IN ZONE 3.
- △.000150 MIN TIN ENTIRE CONTACT.

REV	DATE	DESCRIPTION	BY	CHK
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THIS DRAWING IS A CONTROLLED DOCUMENT.

DATE	10/20/04	BY	10/20/04
CHK	S. BOLASH	APP	10/20/04
DESIGNER	108-9024	PRODUCT SPEC	
APPLICATOR	114-16015	APPLICATION SPEC	
WEIGHT	0.000000		

MATERIAL: PH. BRONZE .010 THK

FINISH: SEE TABLE

STE TE Connectivity

CONTACT, SOLDER TAB, FOC, .100 Q

SIZE: A2

DATE CODE: 00779

DRAWING NO: 88997

RESTRICTED TO: 1st 1st

SCALE: 10:1

SHEET: 1 of 1

REV: Y2